

November 2013

FDB2710

N-Channel PowerTrench® MOSFET 250 V, 50 A, 42.5 m Ω

Features

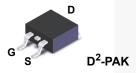
- $R_{DS(on)}$ = 36.3 m Ω (Typ.)@ V_{GS} = 10 V, I_D = 25 A
- High Performance Trench Technology for Extremely Low $R_{\mbox{\footnotesize{DS}}(\mbox{\footnotesize{on}})}$
- · Low Gate Charge
- · High Power and Current Handing Capability

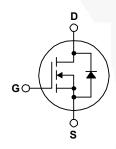
General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's PowerTrench® process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

Applications

- · Synchronous Rectification
- · Battery Protection Circuit
- · Motor Drives and Uninterruptible Power Supplies





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol		Parameter		FDB2710	Unit
V _{DS}	Drain-Source Voltage		250	V	
V _{GS}	Gate-Source voltage		± 30	V	
I _D	Drain Current	- Continuous ($T_C = 25^{\circ}$ Continuous ($T_C = 100^{\circ}$		50 31.3	A A
I _{DM}	Drain Current	- Pulsed	(Note 1)	See Figure 9	A
E _{AS}	Single Pulsed Avala	anche Energy	(Note 2)	145	mJ
dv/dt	Peak Diode Recove	ery dv/dt	(Note 3)	4.5	V/ns
P_{D}	Power Dissipation (T _C = 25°C) - Derate above 25°C		260 2.1	W W/°C	
T _{J,} T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
T _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	FDB2710	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.48	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (minimum pad of 2 oz copper), Max.	62.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (1 in ² pad of 2 oz copper), Max.	40	°C/W

Package Marking and Ordering Information

Device Marking Device		Package	Package Reel Size		Quantity
FDB2710	FDB2710	D ² -PAK	330 mm	24 mm	800 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Conditions	Min	Тур	Max	Unit	
Off Charac	Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V$, $I_D = 250\mu A$, $T_J = 25^{\circ}C$	250			V	
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25°C		0.25		V/°C	
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 250V, V _{GS} = 0V V _{DS} = 250V, V _{GS} = 0V, T _C = 125°C			1 500	μ Α μ Α	
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30V, V _{DS} = 0V			100	nA	
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30V, V _{DS} = 0V			-100	nA	
On Charac	teristics						
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0	4.0	5.0	V	
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D = 25A		36.3	42.5	mΩ	
9 _{FS}	Forward Transconductance	V _{DS} = 10V, I _D = 25A		63		S	
Dynamic C	Characteristics						
C _{iss}	Input Capacitance		\	5470	7280	pF	
C _{oss}	Output Capacitance	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz		426	570	pF	
C _{rss}	Reverse Transfer Capacitance	1 - 1.0ivii iz		97	146	pF	
Switching	Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DD} = 125V, I _D = 50A		80	170	ns	
t _r	Turn-On Rise Time	V_{GS} = 10V, R_{GEN} = 25 Ω		252	515	ns	
t _{d(off)}	Turn-Off Delay Time			112	235	ns	
t _f	Turn-Off Fall Time	(Note 4)		154	320	ns	
Q_g	Total Gate Charge	V _{DS} = 125V, I _D = 50A		78	101	nC	
Q _{gs}	Gate-Source Charge	V _{GS} = 10V	-	34		nC	
Q _{gd}	Gate-Drain Charge	(Note 4)	-/	18		nC	
Drain-Sour	rce Diode Characteristics and Maximum	m Ratings				<u>I</u>	
I _S	S Maximum Continuous Drain-Source Diode Forward Current				50	Α	
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				150	Α	
V _{SD}	Drain-Source Diode Forward Voltage	Source Diode Forward Voltage $V_{GS} = 0V, I_S = 50A$			1.2	V	
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S = 50A		163		ns	
Q _{rr}	Reverse Recovery Charge	dI _F /dt =100A/μs		1.3	//	μС	

Notes:

^{1.} Repetitive Rating: Pulse width limited by maximum junction temperature

^{2.} L = 1mH, I $_{AS}$ = 17A, V $_{DD}$ = 50V, R $_{G}$ = 25 Ω , Starting T $_{J}$ = 25°C

^{3.} $I_{SD} \le 50A$, di/dt $\le 100A/\mu s$, $V_{DD} \le BV_{DSS}$, Starting T_J = 25°C

^{4.} Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

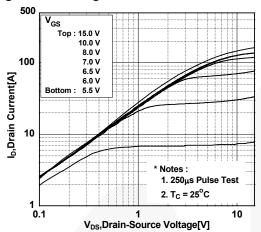


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

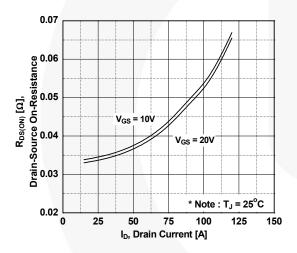


Figure 5. Capacitance Characteristics

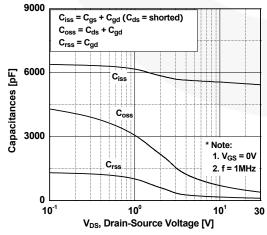


Figure 2. Transfer Characteristics

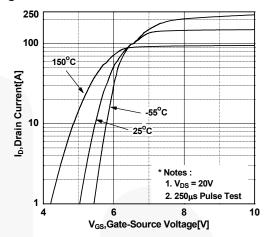


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

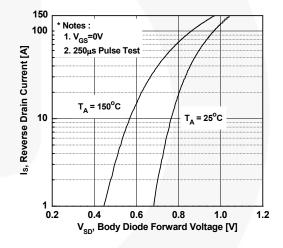
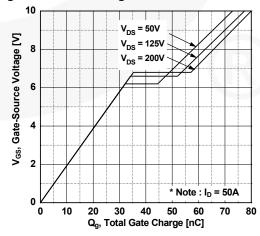


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

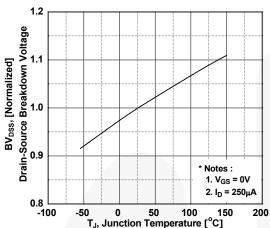


Figure 9. Maximum Safe Operating Area

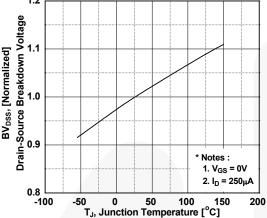


Figure 8. On-Resistance Variation vs. Temperature

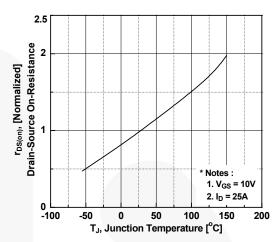
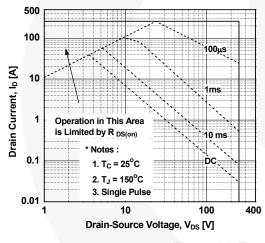


Figure 10. Maximum Drain Current vs. Case Temperature



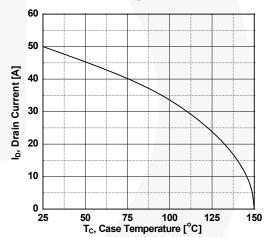


Figure 11. Transient Thermal Response Curve

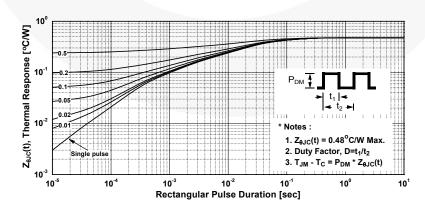


Figure 12. Gate Charge Test Circuit & Waveform

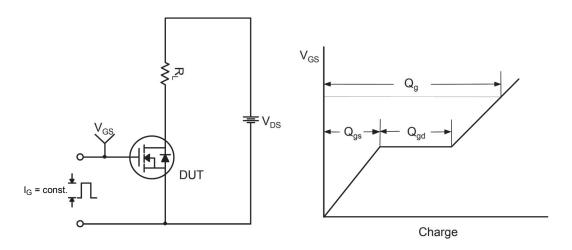


Figure 13. Resistive Switching Test Circuit & Waveforms

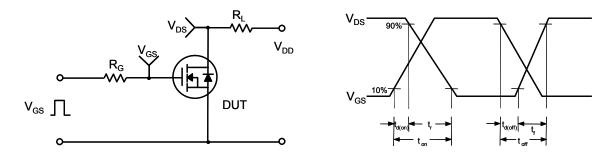


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

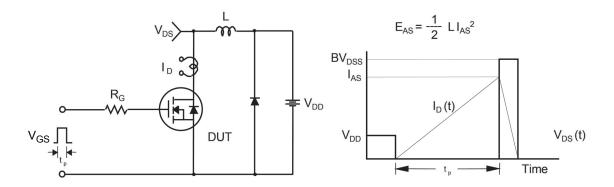
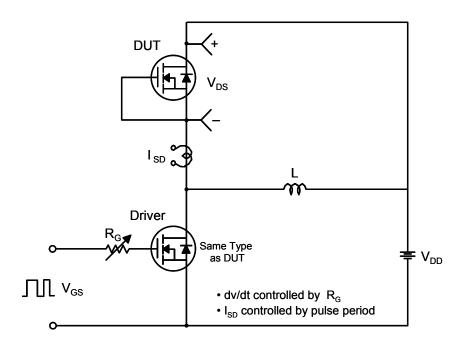
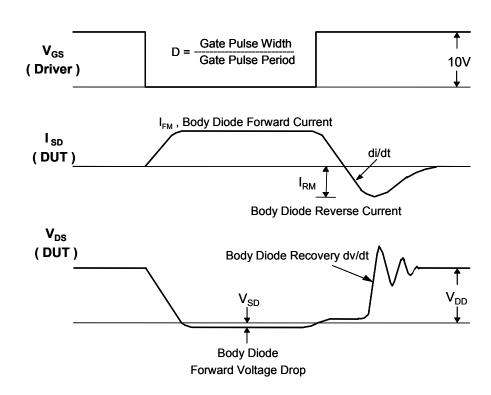


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms





Mechanical Dimensions

TO-263 2L (D²PAK)

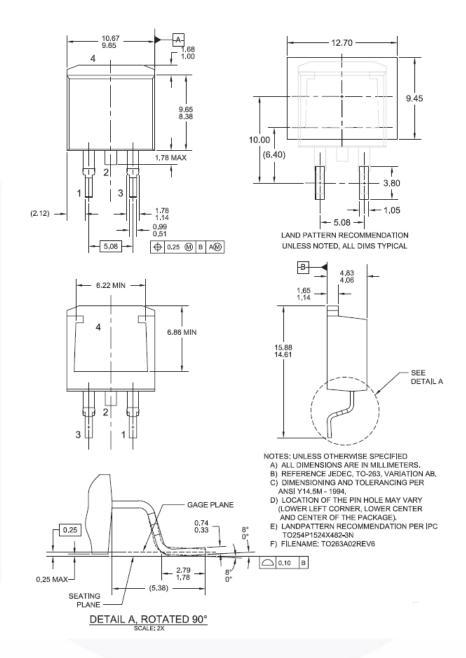


Figure 16. 2LD, TO263, Surface Mount

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Dimension in Millimeters





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